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TI - Aqueous photoresist developer composition or electronics cleaning composition, comprises acetylenic diol ethylene oxide/propylene oxide adduct as surfactant

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AP: 2001EP-0100222 20010102

- **JP2001215690** A 20010810 DW2001-68 Jpn 72p

AP: 2000JP-0401767 20001228

- TW-557418 A 20031011 DW2004-24 Chi

AP: 2001TW-0100043 20010102

- JP2004339226 A 20041202 DW2004-79 Jpn 34p

AP: 2004JP-0185355 20040623, Div Ex 2000JP-0401767 20001228

- TW-245977 B1 20051221 DW2007-07 Chi

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AB - EP1115035 A

NOVELTY: An aqueous photoresist developer composition contains an acetylenic diol ethylene oxide/propylene oxide adduct as a surfactant.

- DESCRIPTION: The surfactant in the photoresist is of formula (I). $r, t = 1$ or 2 ; $n + m = 1-30$; and $p + q = 1-30$. The ethylene oxide units ($n + m$) and propylene oxide units ($p + q$) are distributed in either random or block order. INDEPENDENT CLAIMS are also included for the following: (1) a process for developing a photoresist after exposure to radiation by applying the developer solution containing the surface tension reducing surfactant to the photoresist surface; and (2) an aqueous electronics cleaning composition containing tetramethylammonium hydroxide (0.1-3.0% by weight), a phenolic compound (0-4% by weight) and the surfactant (10-10,000 ppm).
- USE: As a surfactant for use in photoresist development. The water-based compositions are useful as coatings, inks, fountain solutions and agricultural compositions
- ADVANTAGE: The surface tension of the system is reduced and wettability is improved. Foam production is minimized.

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UE - 2001-68; 2004-24; 2004-79; 2007-07

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